POLISHING COMPOSITION

ABSTRACT

A polishing composition includes: an abrasive; a load reducer; a water-soluble polymer; a basic compound; and water. The following expression is satisfied:

$A \times B/C < 2.8$,

where A is the contact angle of a 0.1 mass % aqueous solution of the load reducer relative to the surface of a glass epoxy resin plate with a surface roughness Ra of 3.0 nm, B is the surface tension of a 0.1 mass % aqueous solution of the load reducer, and C is the molecular weight of the load reducer.

[No Available Figure]